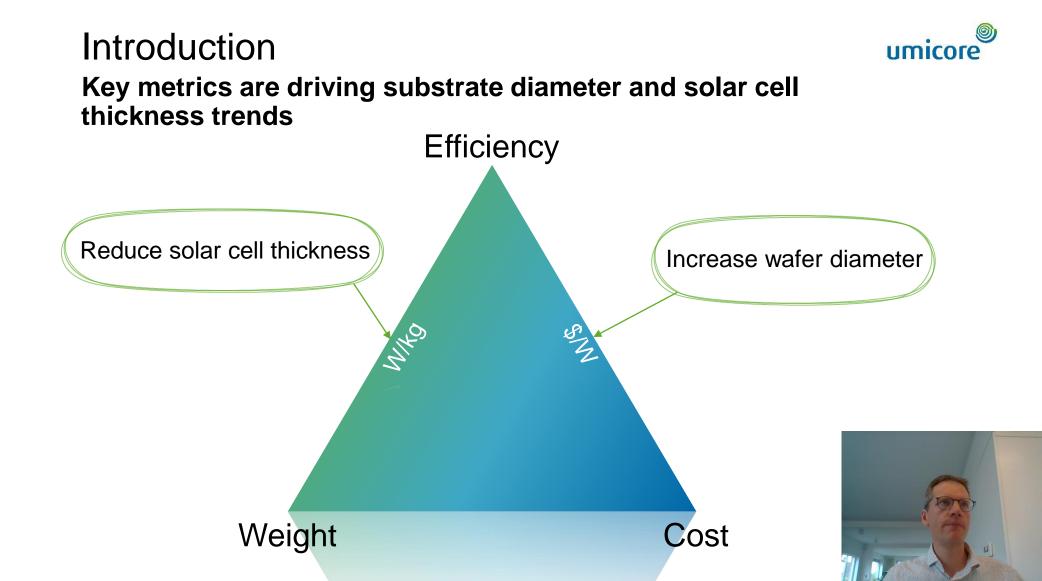


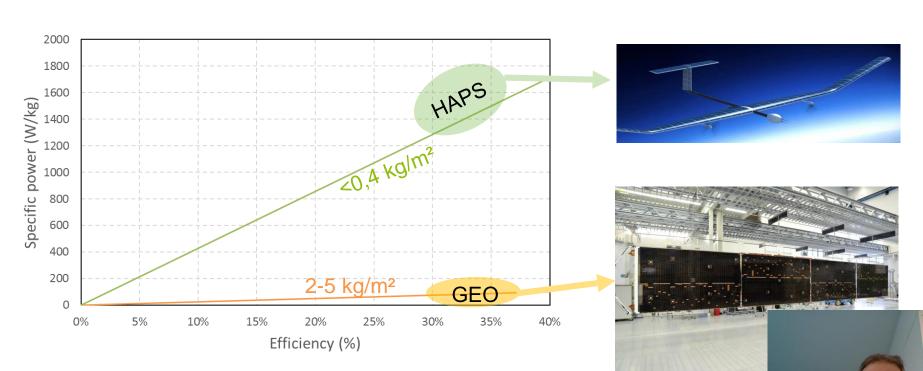
Towards affordable flexible and light weight multi-junction solar cells

K. Dessein, J. Cho, G. Courtois, R. Kurstjens

SPW 2021

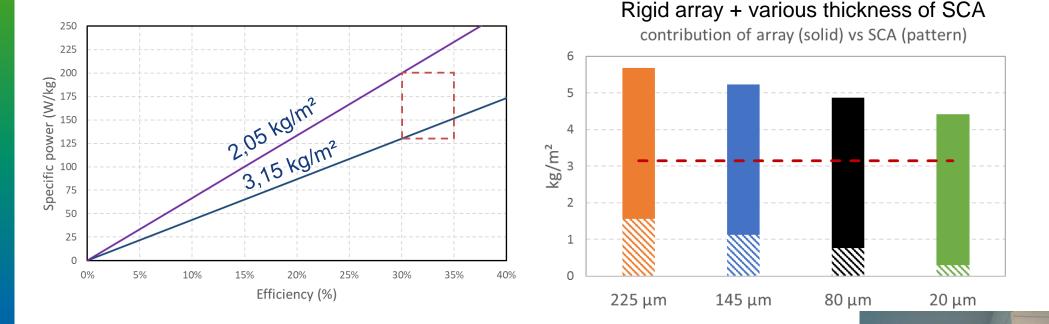








Introduction GEO target 130-200 W/kg

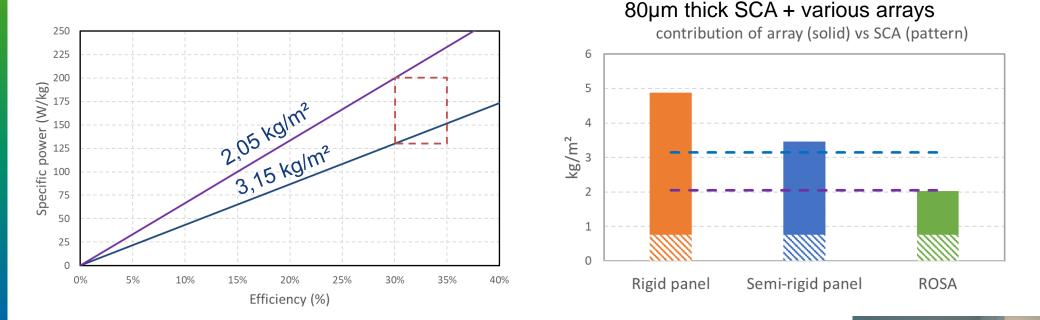


Reduction in Ge thickness isn't enough by itself

Development of a New, High-Power Solar Array for Telecommunication Satellites, C.G. Zimmermann, E3S Web Conf. 16 01006 (2017)



Introduction GEO target 130-200 W/kg → thin SCA is enabler





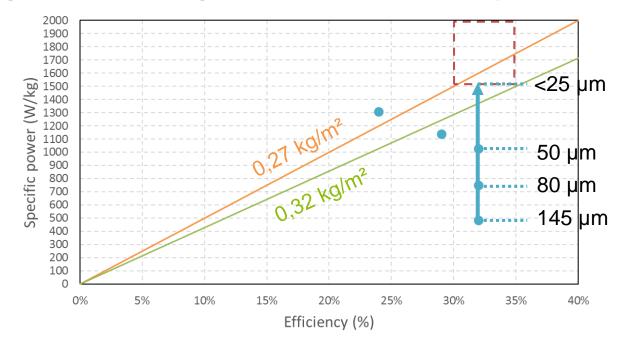
combine with transition from rigid to semi-rigid array or ROSA

Development of a New, High-Power Solar Array for Telecommunication Satellites, C.G. Zimmermann, E3S Web Conf. 16 01006 (2017)





HAPS targets ~1500 W/kg > thin SCA mandatory!



https://solaerotech.com/wp-content/uploads/2018/03/UAV-Spec-Sheet-April-2017.pdf

http://mldevices.com/index.php/product-services/photovoltaics

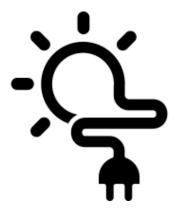
Introduction

https://www.altadevices.com/technology/



How thick should a Ge substrate be? Ge substrate has 2 functions

Choice of thickness impacts 2 of the jobs that the Ge wafer must perform:





solar cell functionality

mechanical support

How much Ge is needed for each?

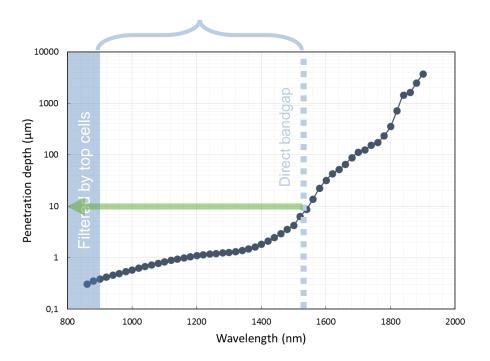






How thick should a Ge substrate be? How much Ge is needed for the bottom cell in a TJ cell?

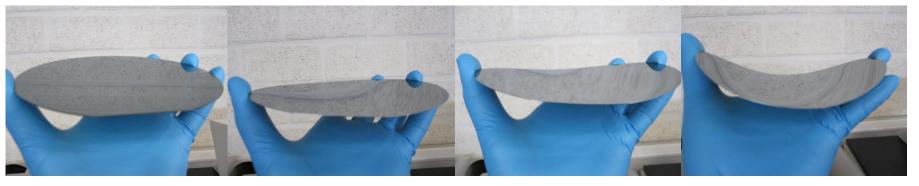
available current ~30 mA/cm²





5-10 µm of Ge is sufficient for the device... but what about mechanical support?

How thick should a Ge substrate be? Substrate bow due to gravitation ~ r²/t³



625 µm

190 µm

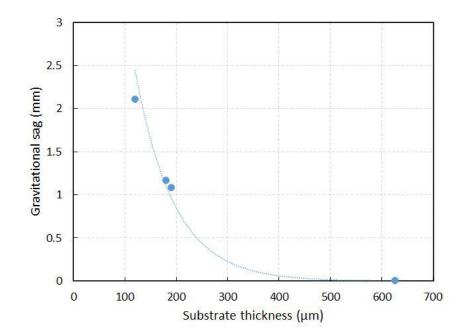
180 µm

120 µm





How thick should a Ge substrate be? Substrate bow due to gravitation ~ r²/t³





4" wafer	6" wafer
135 µm	225 μm



Thinning options

Substraction

• End-of-line thinning by (Taiko) grinding

Addition

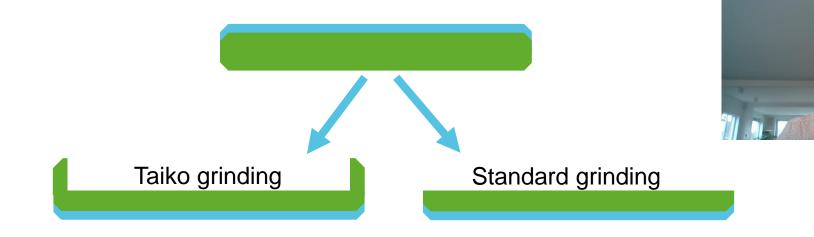
- ELO
- Weak layer

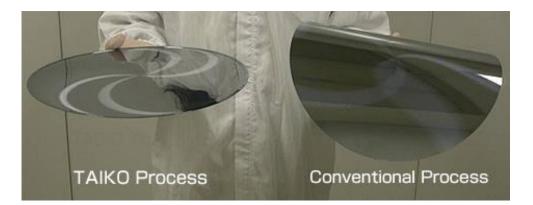


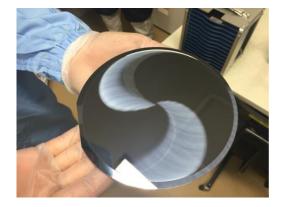


End of line thinning: (Taiko) grinding



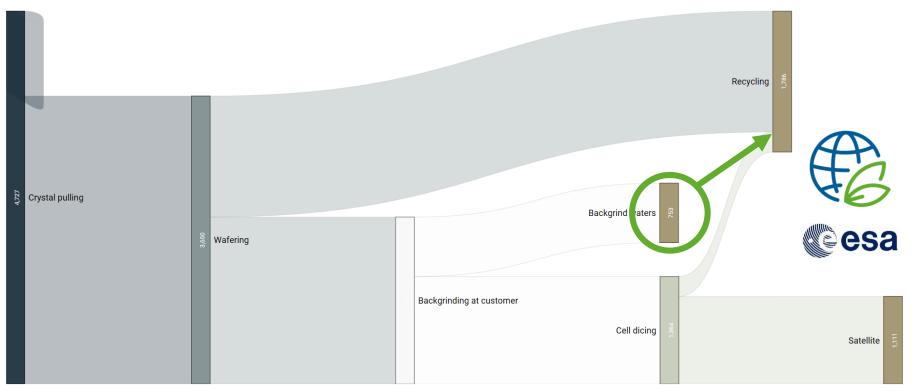




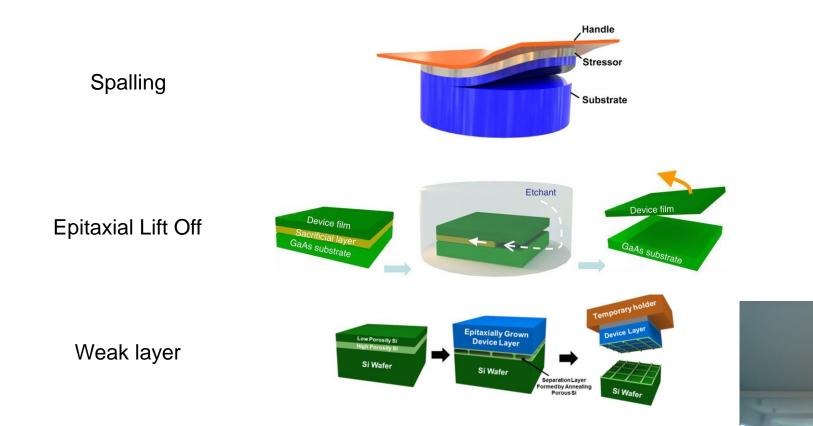


End-of-line wafer thinning Ge mass balance: 100.000 wafers, 150 mm, 225 µm → 145 µm





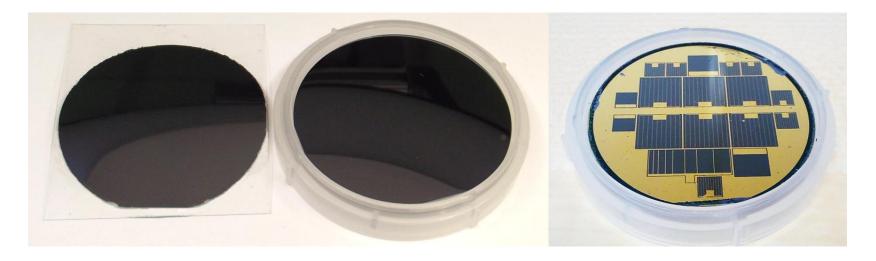
Lift-Off techniques Transfer mechanical support function to other material + substrate re-use







Lift-Off techniques Epitaxial Lift Off: lifting GaAs layers of from Ge substrates



Demonstration of ELO thin-film (left) from a Ge wafer (right)





EIT RawMaterials is supported by the EIT, a body of the European Union





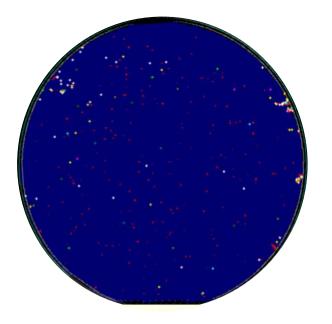
tf2 devices

Cells processed from the ELO thin-film after replacement of the flexible foil handle with a rigid carrier to facilitate processing



umie

Lift-off techniques Epitaxial Lift Off: Proven technology



Surfscan of Ge wafer before 3rd epitaxial growth.





EIT RawMaterials is supported by the EIT, a body of the European Union

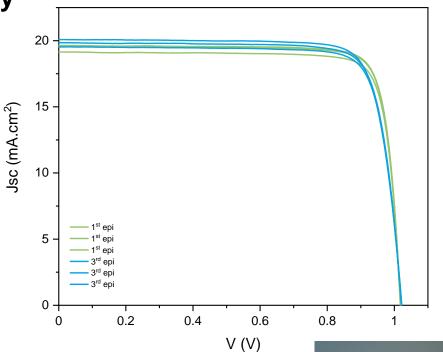






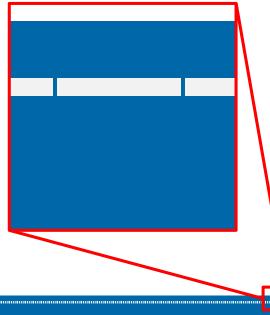
JV-characteristics of thin-film GaAs solar cells grown on a new Ge wafer $(1^{st} epi)$ and on a reused Ge wafer $(3^{rd} epi)$. 1 cm² without ARC.





Lift-off techniques Umicore concept wafer: Ge-on-Ge engineered substrate





1 – 30 µm Ge foil

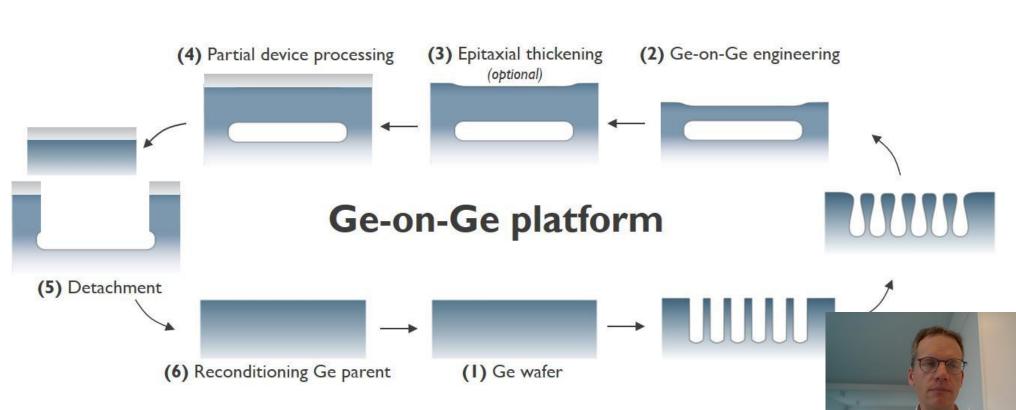
Flexible doping profile

Weak layer that allows easy detachment

Ge-on-Ge engineered substrate goes into MOCVD

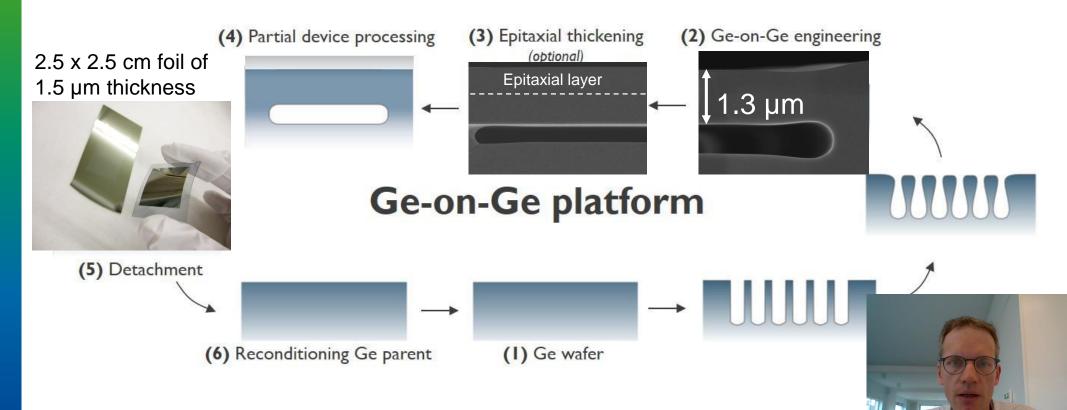


Ge-on-Ge engineered substrate Process flow





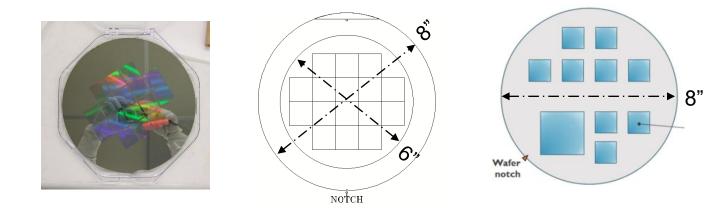
Ge-on-Ge engineered substrate Process flow





Ge-on-Ge engineered substrate Work done on full wafer substrate size



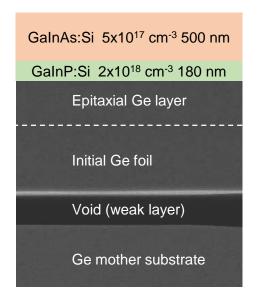




Activity carried out under a program of, and funded by, the European Space Agency.



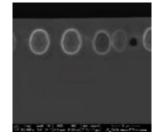
Ge-on-Ge engineered substrate MOCVD growth results



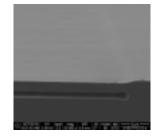


Activity carried out under a program of, and funded by, the European Space Agency.

Sample A



Sample B



POLITÉCNICA

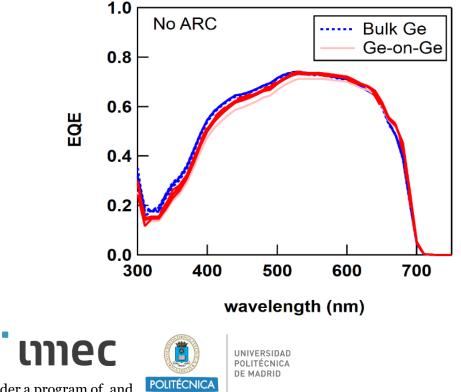
UNIVERSIDAD POLITÉCNICA DE MADRID Process maintains monocrystalline nature

- Process maintains 6 degrees off-cut
- No flaking or collapsing observed during growth





Ge-on-Ge engineered substrate MOCVD growth results





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Activity carried out under a program of, and funded by, the European Space Agency.

esa



Connecting Life

